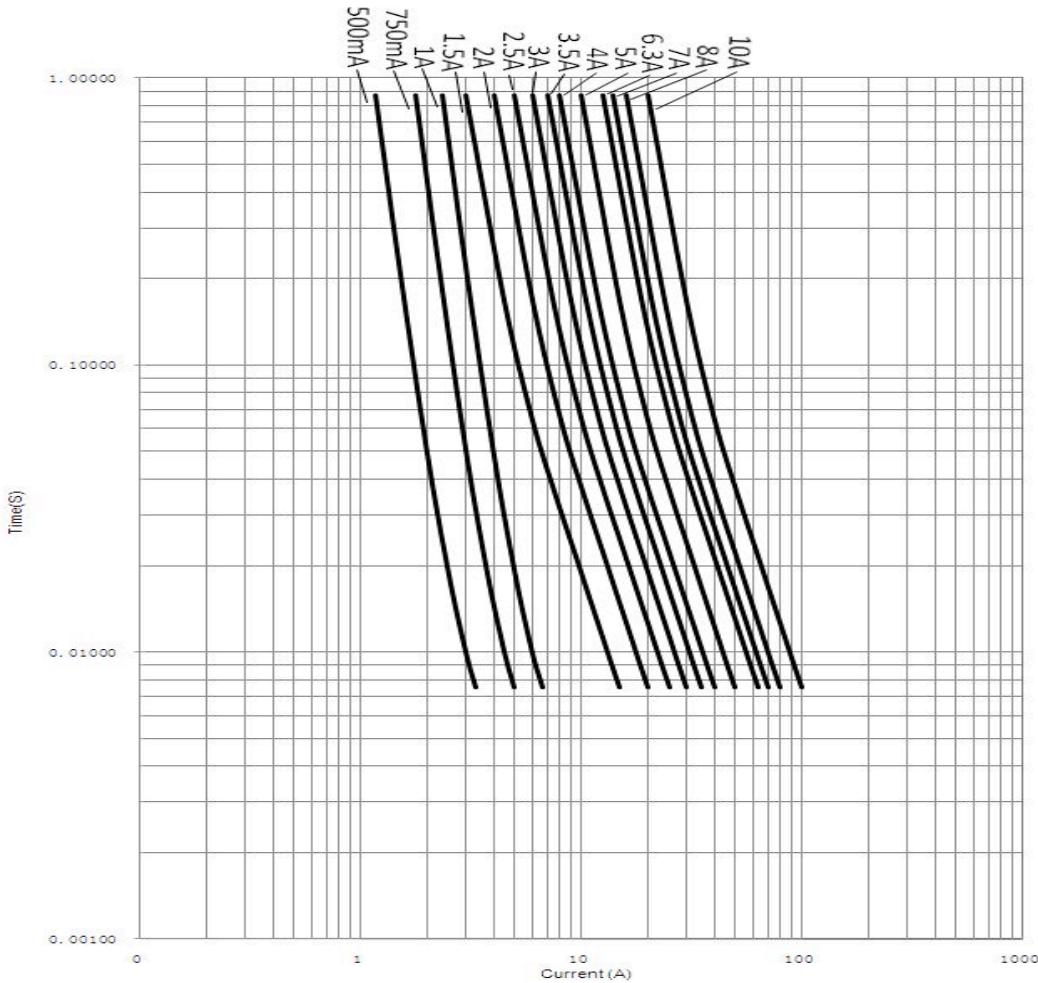
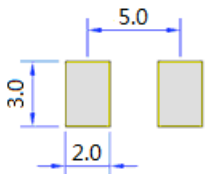


Time Current Curve



Land Pattern (mm)



Soldering Method

- Wave soldering: 260°C, 10sec max.
- Reflow soldering: 260°C, 30sec max.

Environmental Data

- Life Test: MIL-STD-202, Method 108D
- Humidity Bias: MIL-STD-202, Method 103
- Moisture Resistance Test: MIL-STD-202, Method 106G
- Thermal Shock: MIL-STD-202, Method 107G
- Terminal Strength: AEC-Q200-006
- Board Flex: AEC-Q200-005 Appendix 2 Note: 1mm (Min)
- Vibration: MIL-STD-202, Method 204C
- Mechanical Shock: MIL-STD-202, Method 213C
- Solderability: ANSI/J-STD-202
- Resistance to Solder Heat: MIL-STD-202, Method 210B
- Resistance to Solvents Test: MIL-STD-202, Method 215